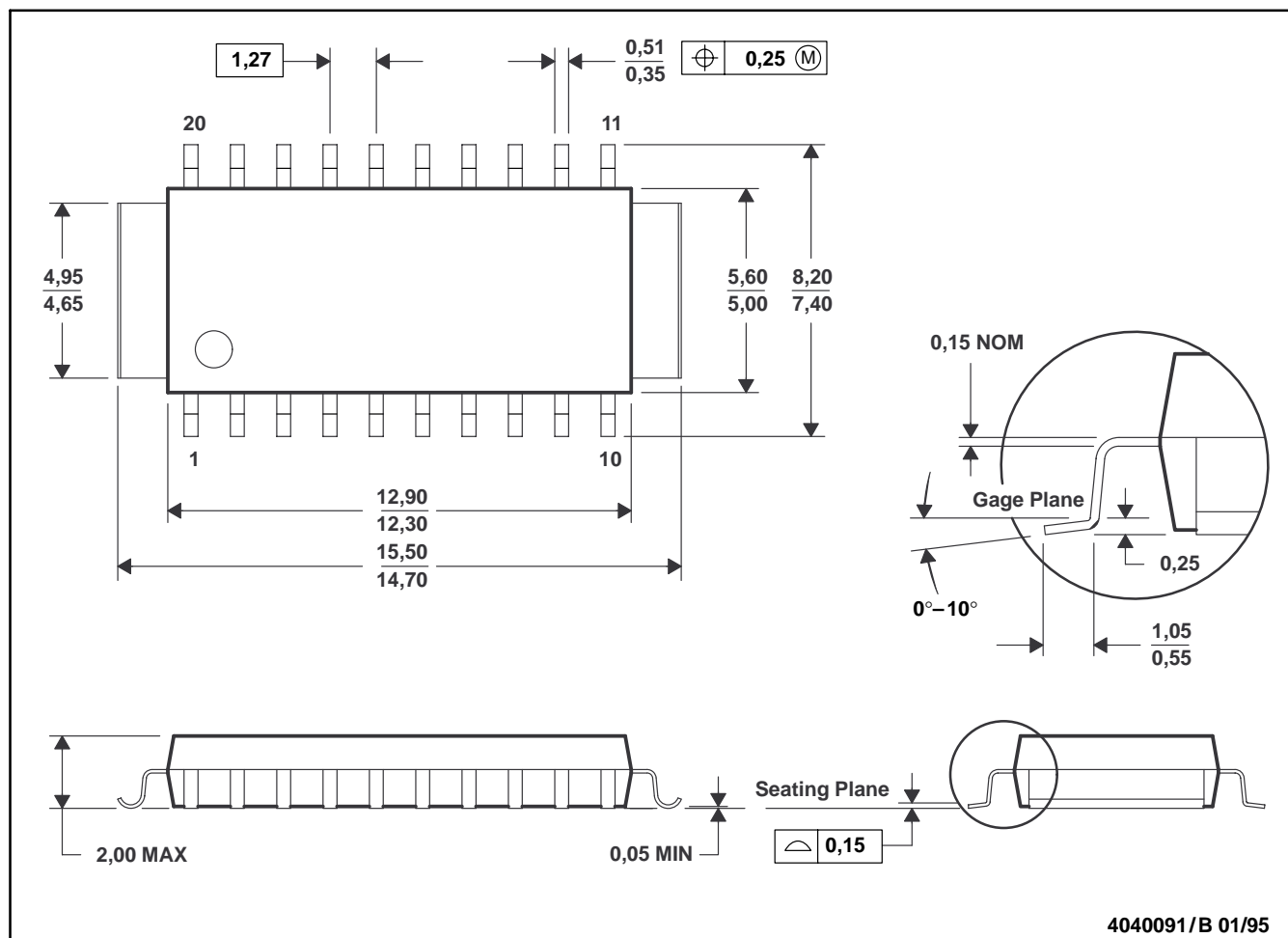


## DSA (R-PDSO-G20)

## PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion.
  - D. Thermally enhanced molded plastic package with end tabs connected to die pad

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